

POWER DISSIPATION (DFN1212-4)

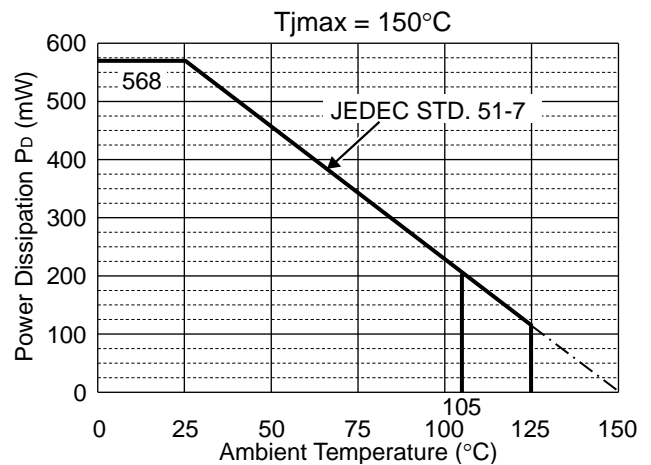
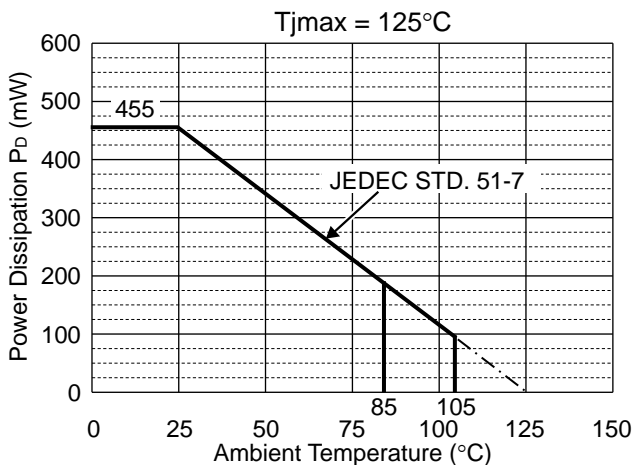
Power Dissipation (P_D) depends on conditions of mounting on board.
 This specification is based on the measurement at the condition below:

Measurement Conditions

	JEDEC STD.51-7 Test Land Pattern
Environment	Mounting on board (Wind velocity = 0m/s)
Board Material	Glass cloth epoxy plastic (4 layers)
Board Dimensions	76.2 mm x 114.3 mm x 1.6 mm
Copper Ratio	Top side, Back side : 60 mm square : Approx.10% 2nd, 3rd 74.2 mm square : Approx. 100%
Through-holes	ϕ 0.85 mm x 44 pcs

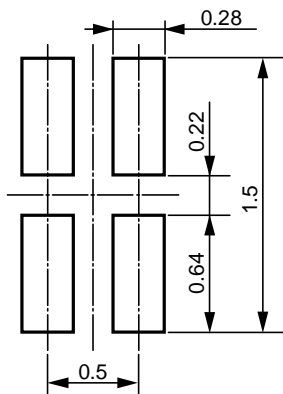
Measurement Results ($T_a = 25^\circ\text{C}$)

	JEDEC STD.51-7 Test Land Pattern
Power Dissipation	455 mW ($T_{jmax} = 125^\circ\text{C}$) 568 mW ($T_{jmax} = 150^\circ\text{C}$)
Thermal Resistance	$\theta_{ja} = 220^\circ\text{C/W}$ $\theta_{jc} = 68^\circ\text{C/W}$

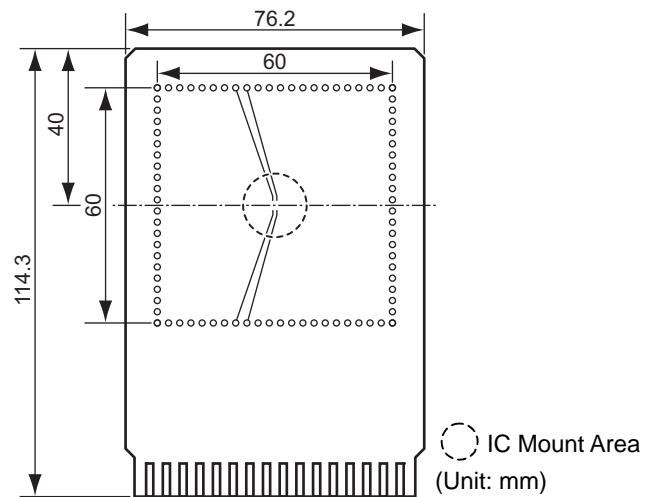


Power Dissipation vs. Ambient Temperature

RECOMMENDED LAND PATTERN



(Unit: mm)



Measurement Board Pattern